Advanced Semiconductor Pakaging & Chiplet Show



ASPS 2024 Post-Show Report

01 OVERVIEW



SHOW TITLE Advanced Semiconductor Packaging Show 2024

ACRONYM ASPS 2024

MANAGED BY

SUPPORTED BY

DATE August 28-30, 2024

VENUE Suwon Convention Center

SCALE 168 exhibitors, 328 booths

VISITOR 9,467 unique visitors

ORGANIZED BY Gyeonggi-do, Suwon City

J. Expo, Suwon Convention Center, Electronic Times

Ministry of Science and ICT, Korea Semiconductor Industry Association, Korea Packaging Integration Association, Advanced Institute of Convergence Technology, Korea Advanced Nano Fab Center, Korea Electronics Technology Institute,

The Korean Association of Microelectronics Packaging,

The Korean Microelectronics and Packaging Society,

SoBuJang Technology Collaboration Forum,

Hanyang Center for Advanced Semiconductor Packaging, HYU LINC 3.0







02 SHOW HIGHLIGHTS



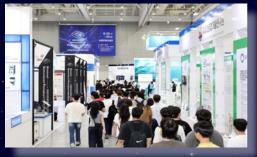
Unique Visitors 9,467

No. of Exhibitors 168

No. of Booths

328







KEY VISITORS

- ·ALT
- · AMKOR TECHNOLOGY
- · APACT
- · ASE KOREA
- ·ASML
- · DB HITEK
- · DENSO
- · DONGWOO FINE-CHEM
- · DOOSAN TESNA
- · HANA MICRON
- ·HANWHA NXMD
- ·HYUNDAI MOBIS
- ·HYUNDAI MOTOR
- ·INTEL
- ·ITEK
- · JCET STATS CHIPPAC KOREA
- ·LB LUSEM
- · LB SEMICON
- · LG ELECTRONICS
- · LG INNOTEK

- ·MCNEX
- **· MEMSPACK**
- · NEPES
- · NEPES ARK
- · NEPES LAWEH
- **PARTRON**
- ·QUALCOMM
- ·SAMSUNG
- ·SAMSUNG ELECTRO-MECHANICS
- ·SAMSUNG SDI
- · SAPIEN SEMICONDUCTORS
- ·SFA SEMICON
- · SIEMENS
- · SIGNETICS
- ·SK HYNIX
- · SKAICHIPS
- ·STECO
- ·TEKLINE KOREA
- · TEXAS INSTRUMENTS
- ·WINPAC

03 CONCURRENT EVENTS



Over 2,000 people attended as part of the concurrent event.













EXHIBITORS ANALYSIS













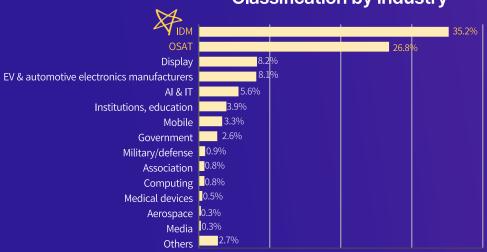
05 VISITORS ANALYSIS



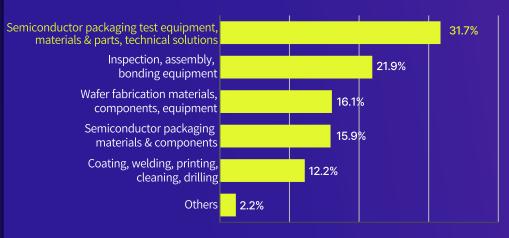








Products of Interest



06 POST-SHOW SURVEY





VISITOR FEEDBACK



EXHIBITOR FEEDBACK



The convenient location and the opportunity to gain insights into market trends made it a valuable experience.



I appreciated the opportunity to connect with clients we were collaborating with and exploring.



It was an opportunity to learn about various companies in the semiconductor industry and share information.



I was pleased with the many visits from professionals in semiconductor packaging.



The concurrent event was substantial and informative, allowing me to deepen my understanding of the semiconductor industry.



I was able to gain a great promotional opportunity through participation in the exhibition, and it will likely be beneficial for future marketing as well.

COMING UP NEXT SHOW



Advanced

Semiconductor Packaging & Chiplet Show

2025. 8. 27(WED) - 8. 29(FRI), Suwon Convention Center